A New Era of Silicon Prototyping in Computer Architecture Research

Christopher Torng

Computer Systems Laboratory
School of Electrical and Computer Engineering
Cornell University
Recent History of Prototypes at Cornell University
Recent History of Prototypes at Cornell University

- **DCS (2014)**
  - TSMC 65nm
  - 1mm x 2.2mm

- **BRGTC1 (2016)**
  - IBM 130nm
  - 2mm x 2mm
Recent History of Prototypes at Cornell University

- **DCS (2014)**
  - TSMC 65nm
  - 1mm x 2.2mm

- **BRGTC1 (2016)**
  - IBM 130nm
  - 2mm x 2mm

- **Celerity (2017)**
  - TSMC 16nm FinFET
  - 5mm x 5mm
Recent History of Prototypes at Cornell University

DCS (2014)
TSMC 65nm
1mm x 2.2mm

BRGTC1 (2016)
IBM 130nm
2mm x 2mm

Celerity (2017)
TSMC 16nm FinFET
5mm x 5mm

BRGTC2 (2018)
TSMC 28nm
1mm x 1.25mm
Recent History of Prototypes at Cornell University

- **DCS (2014)**
  - TSMC 65nm
  - 1mm x 2.2mm

- **BRGTC1 (2016)**
  - IBM 130nm
  - 2mm x 2mm

- **Celerity (2017)**
  - TSMC 16nm FinFET
  - 5mm x 5mm

- **BRGTC2 (2018)**
  - TSMC 28nm
  - 1mm x 1.25mm

- **PCOSYNC (2018)**
  - IBM 180nm
  - 2mm x 1mm
Recent History of Prototypes at Cornell University

**Why Prototype?**

**Research Ideas**

- Smart Sharing Architectures
- Interconnection Networks for Manycores
- Python-Based Hardware Modeling
- High-Level Synthesis
- Synthesizable Analog IP
- Scalable Baseband Synchronization
- Integrated Voltage Regulation
Recent History of Prototypes at Cornell University

**Why Prototype?**

**Chip-Based Startups**

- Graphcore
- Nervana
- Cerebras
- Wave Computing
- Horizon Robotics
- Cambricon
- DeePhi
- Esperanto
- SambaNova
- Eyeriss
- Tenstorrent
- Mythic
- ThinkForce
- Groq
- Lightmatter
**Chip Overview**

- TSMC 28 nm
- 1 mm × 1.25 mm
- 6.7M-transistor
- Quad-core in-order RISC-V RV32IMAF
- Shared L1 caches (32kB) Shared LLFUs
- Designed and tested in PyMTL (Python-based hardware modeling)
- Fully synthesizable PLL
- Smart sharing mechanisms
- Hardware bloom filter xcel
- Runs work-stealing runtime
Key Changes Driving A New Era

**Ecosystems for Open Builders**

**Problem:** Closed tools & IP makes dev tough  
**Changes:** Open-source ecosystem with RISC-V

**Productive Tools for Small Teams**

**Problem:** Small teams with a limited workforce  
**Changes:** Productive & open tool development

**Significantly Cheaper Costs**

**Problem:** Building chips is expensive  
**Changes:** MPW tiny chips in advanced nodes
**Problem:** A closed-source chip-building ecosystem (tools & IP) makes chip development tough

---

**Problems with Closed-Source Infrastructure**

- Difficult to replicate results (including your own)
- Anything closed-source propagates up and down the stack
  - E.g., modified MIPS ISA
  - Spill-over to other stages of the design flow
- Heavy impact on things I care about
  - Sharing results and artifacts
  - Portability
  - Maintenance
- Reinventing the wheel

How important is a full ecosystem?
Ecosystems for Open Builders

Key Change: The open-source ecosystem revolving around RISC-V is growing

The RISC-V Ecosystem

► Software toolchain and ISA
  ▶ Linux, compiler toolchain, modular ISA

► Cycle-level modeling
  ▶ gem5 system-level simulator supports RISC-V multicore
  ▶ We can now model complex RISC-V systems

► RTL modeling
  ▶ Open implementations and supporting infrastructure
    (e.g., Rocket, Boom, PULP, Diplomacy, FIRRTL, FireSim)

► ASIC flows
  ▶ Reference flows available from community for inspiration
Ecosystems for Open Builders

How has the RISC-V ecosystem helped in the design of BRGTC2?

BRGTC2 in the RISC-V Ecosystem

- Software toolchain and ISA
  - Not booting Linux...
  - Upstream GCC support
  - Incremental design w/ RV32 modularity

- Cycle-level modeling
  - Multicore gem5 simulations of our system
  - **Decisions**: L0 buffers, how many resources to share, impact of resource latencies, programs fitting in the cache

- RTL modeling
  - This was our own...

- ASIC flows
  - Reference methodologies available from other projects (e.g., Celerity)
Key Changes Driving A New Era

Ecosystems for Open Builders

**Problem:** Closed tools & IP makes dev tough  
**Changes:** Open-source ecosystem with RISC-V

Productive Tools for Small Teams

**Problem:** Small teams with a limited workforce  
**Changes:** Productive & open tool development

Significantly Cheaper Costs

**Problem:** Building chips is expensive  
**Changes:** MPW tiny chips in advanced nodes
**Problem**: Small teams have a limited workforce and yet must handle challenging projects

---

**An Enormous Challenge for Small Teams**

- Small teams exist in both academia as well as in industry
- Time to first tapeout can be anywhere up to a few years
- What do big companies do?
  - Throw money and engineers at the problem
- Generally stuck with tools that “work”
  - If you have enough engineers
  - E.g., System Verilog
Productive Tools for Small Teams

**Key Change:** Productive open-source tools progressing and maturing quickly

---

### Focusing on BRGTC2

- **PyMTL Hardware Modeling Framework**
  - Python-based hardware design and test
  - Beta version of PyMTL v2
  - [https://github.com/cornell-brg/pymtl](https://github.com/cornell-brg/pymtl)

- **The Open Modular VLSI Build System**
  - Two chips taped out (180nm/28nm)
  - Reference ASIC flow available
  - [https://github.com/cornell-brg/alloy-asic](https://github.com/cornell-brg/alloy-asic)

- **Fully Synthesizable PLL**
  - To be open-sourced soon
  - All-digital PLL used in BRGTC2/Celerity
  - Avoid mixed-signal design

Derek Lockhart, Gary Zibrat, Christopher Batten
47th ACM/IEEE Int’l Symp. on Microarchitecture (MICRO)

Mamba: Closing the Performance Gap in Productive Hardware Development Frameworks

Shunning Jiang, Berkin Ilbeyi, Christopher Batten
55th ACM/IEEE Design Automation Conf. (DAC)
San Francisco, CA, June 2018
**Problem:** Rigid, static ASIC flows

**Typical ASIC Flows**

- Flows are automated for exact sequences of steps
  - Want to add/remove a step? Modify the build system. Copies..
  - Once the flow is set up, you don’t want to touch it anymore

- Adding new steps between existing steps is troublesome
  - Steps downstream magically reach upstream — hardcoding
  - In general, the overhead to add new steps is high

- Difficult to support different configurations of the flow
  - E.g., chip flow vs. block flow
  - How to add new steps before or after
  - Each new chip ends up with a dedicated non-reusable flow
Better ASIC Flows – Modularize the ASIC flow!

- Use the build system to mix, match, and assemble steps together
  - Create modular steps that know how to run/clean themselves
  - The build system can also check prerequisites and outputs before and after execution to make sure each step can run

- Assemble the ASIC flow as a graph
  - Can target *architecture* papers by assembling a minimal graph
  - Can target *VLSI* papers by assembling a medium graph w/ more steps (e.g., need dedicated floorplan)
  - Can target a *chip* by assembling a full-featured tapeout graph
Simple Front-End-Only ASIC Flow

* seed
  * dc-synthesis
  * innovus-flowsetup
    * innovus-init
    * innovus-place
    * innovus-cts
    * innovus-postctshold
    * innovus-route
    * innovus-postroute
    * innovus-signoff
  * calibre-gds-merge
    * calibre-lvs
    * calibre-drc
BRGTC2 ASIC Flow

```
* seed
  |* info
  | */ gen-sram-verilog
  | */ sim-prep
  |   | */ vcs-rtl-build
  |   | */ vcs-rtl
  |   | */ vcs-aprsdfx-build
  |   | */ vcs-aprsdf
  |   | */ vcs-aprsdf-build
  |   | */ gen-sram-lib
  |   | */ dc-synthesis
  |   | */ gen-sram-flowsetup
  |   |* innovus-flowsetup
  | */ gen-sram-lef
  | */ gen-sram-db
  |* innovus-init
  |* innovus-place
  |* innovus-cts
  |* innovus-postctshold
  |* innovus-route
  |* innovus-postroute
  |* innovus-signoff
  |* pt-signoff
  |* gen-sram-gds
  |* calibre-seal
  |* calibre-fill
  |* calibre-stamp
  |* mosis
  |* gen-sram-cdl
  |* calibre-lvs-top
  |* calibre-lvs-sealed
  |* calibre-lvs
  |* calibre-drc-top
  |* calibre-drc-sealed
```
Key Changes Driving A New Era

___ Ecosystems for Open Builders ___

**Problem:** Closed tools & IP makes dev tough  
**Changes:** Open-source ecosystem with RISC-V

___ Productive Tools for Small Teams ___

**Problem:** Small teams with a limited workforce  
**Changes:** Productive & open tool development

___ Significantly Cheaper Costs ___

**Problem:** Building chips is expensive  
**Changes:** MPW tiny chips in advanced nodes
Significantly Cheaper Costs

**Problem**: Building chips is expensive

**Key Change**: Multi-project wafer services offer advanced node runs with small minimum sizes

Snapshot from Muse Semiconductor

<table>
<thead>
<tr>
<th>Tech (nm)</th>
<th>Flavor</th>
<th>Min Area (mm²)</th>
<th>Price ($/mm²)</th>
<th>Trial</th>
<th>Final</th>
<th>Tapeout</th>
<th>Est. Ship</th>
</tr>
</thead>
<tbody>
<tr>
<td>180</td>
<td>MS RF G</td>
<td>5</td>
<td>1000</td>
<td>8/22/18</td>
<td>8/29/18</td>
<td>9/5/18</td>
<td>10/17/18</td>
</tr>
<tr>
<td>180</td>
<td>MS RF G</td>
<td>5</td>
<td>1000</td>
<td>10/24/18</td>
<td>10/31/18</td>
<td>11/7/18</td>
<td>12/19/18</td>
</tr>
<tr>
<td>65</td>
<td>MS RF GP</td>
<td>1</td>
<td>4700</td>
<td>9/24/18</td>
<td>10/1/18</td>
<td>10/8/18</td>
<td>12/17/18</td>
</tr>
<tr>
<td>65</td>
<td>MS RF GP</td>
<td>1</td>
<td>4700</td>
<td>10/24/18</td>
<td>10/31/18</td>
<td>11/7/18</td>
<td>1/16/19</td>
</tr>
<tr>
<td>65</td>
<td>MS RF GP</td>
<td>1</td>
<td>4700</td>
<td>11/21/18</td>
<td>11/28/18</td>
<td>12/5/18</td>
<td>2/13/19</td>
</tr>
<tr>
<td>65</td>
<td>MS RF LP</td>
<td>1</td>
<td>4700</td>
<td>9/24/18</td>
<td>10/1/18</td>
<td>10/8/18</td>
<td>12/17/18</td>
</tr>
<tr>
<td>65</td>
<td>MS RF LP</td>
<td>1</td>
<td>4700</td>
<td>10/24/18</td>
<td>10/31/18</td>
<td>11/7/18</td>
<td>1/16/19</td>
</tr>
<tr>
<td>40</td>
<td>MS RF G</td>
<td>1</td>
<td>7250</td>
<td>10/17/18</td>
<td>10/24/18</td>
<td>10/31/18</td>
<td>1/20/19</td>
</tr>
<tr>
<td>28</td>
<td>HPC RF</td>
<td>1</td>
<td>14000</td>
<td>10/31/18</td>
<td>11/7/18</td>
<td>11/14/18</td>
<td>2/3/19</td>
</tr>
</tbody>
</table>

Send us an [e-mail](mailto:) to reserve area or request information.
BRGTC2 Timeline and Costs

Time breakdown

▶ One month for one student to pass DRC/LVS for dummy logic with staggered IO pads and no SRAMs
▶ One-month period with seven graduate students using PyMTL for design, test, and composition

Seven graduate students working across:

▶ Applications development
▶ Porting an in-house work-stealing runtime to RISC-V target
▶ Cycle-level design-space exploration with gem5
▶ RTL development and testing of each component including SRAMs
▶ Composition testing at RTL and gate level
▶ SPICE-level modeling of the synthesizable PLL
▶ IO floorplanning
▶ Physical design and post-PnR performance tuning
BRGTC2 Timeline and Costs

Cost breakdown

- $1 \times 1.25$ mm die size and one hundred parts for about $18K$ under the MOSIS Tiny2 program
- Packaging costs (about $2K$ for twenty parts)
- Board costs (less than $1K$ for PCB and assembly)
- Graduate student salaries
- Physical IP costs
- EDA tool licenses
A New Era of Silicon Prototyping in Computer Architecture Research

Key Takeaways

▶ Building silicon prototypes is traditionally challenging and costly
▶ Challenges have significantly reduced
  ▸ Ecosystems for open builders (based on RISC-V)
  ▸ Productive tools for small teams (e.g., PyMTL, ASIC flows)
▶ Costs have significantly reduced
  ▸ MPW services support small minimum sizes in advanced nodes
▶ It is now feasible and attractive to consider RISC-V silicon prototypes for supporting future research

Acknowledgements

▶ NSF CRI Award #1512937
▶ NSF SHF Award #1527065
▶ DARPA POSH Award #FA8650-18-2-7852
▶ Donations from Intel, Xilinx, Synopsys, Cadence, and ARM
▶ Thanks: U.C. Berkeley, RISC-V Foundation, Shreesha Srinath
Backup Slides